

IGTH/IGTM/IGTP20N40
IGTH/IGTM/IGTP20N40A

IGTH/IGTM/IGTP20N50
IGTH/IGTM/IGTP20N50A

File Number 2174

N-Channel Enhancement-Mode Conductivity-Modulated Power Field-Effect Transistors

20 A, 400 V and 500 V

$V_{CE(on)}$: 2.5 V

T_{rr} : 1 μ s, 0.5 μ s

Features:

- Low on-state voltage
- Fast switching speeds
- High input impedance
- No anti-parallel diode

Applications:

- Power supplies
- Motor drives
- Protection circuits

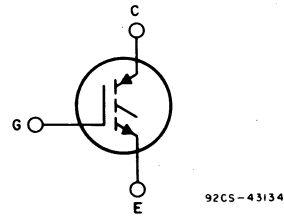
The RCH20N40, RCH20N40A, RCH20N50, RCH20N50A, RCP20N40, RCP20N40A, RCP20N50, RCP20N50A, RCM20N40, RCM20N40A, RCM20N50, RCM20N50A* are n-channel enhancement-mode conductivity-modulated power field-effect transistors designed for high-voltage, low on-dissipation applications such as switching regulators and motor drivers. These types can be operated directly from low-power integrated circuits.

The RCH-types are supplied in the JEDEC TO-218AC plastic package and the RCP-types in the JEDEC TO-220AB plastic package.

The RCM-types are supplied in the JEDEC TO-204AA steel package.

*The RCH and RCP series were formerly RCA Development Type Nos. TA9573XD and TA9573XV, respectively. The RCM series was formerly RCA Development Type No. TA9573XG.

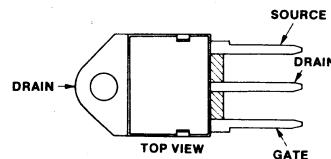
TERMINAL DIAGRAM



92CS-43134

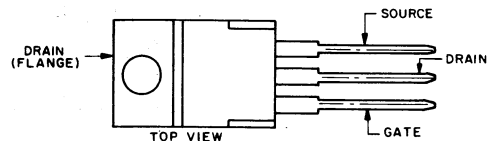
N-CHANNEL ENHANCEMENT MODE

TERMINAL DESIGNATION



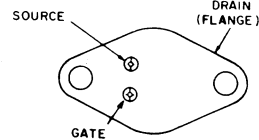
92CS-39987

JEDEC TO-218AC



92CS-39928

JEDEC TO-220AB



92CS-37801

JEDEC TO-204AA

MAXIMUM RATINGS

Absolute-Maximum Values ($T_C = 25^\circ\text{C}$):

	IGTH20N40 IGTH20N40A	IGTM20N40 IGTM20N40A	IGTP20N40 IGTP20N40A	IGTP20N50 IGTP20N50A	
COLLECTOR-EMITTER VOLTAGE, V_{CES}	400	500	400	500	V
COLLECTOR-GATE VOLTAGE ($R_{ge} = 1\text{ M}\Omega$), V_{CGR}	400	500	400	500	V
REVERSE COLLECTOR-EMITTER VOLTAGE, $V_{CES(rev)}$..			-5		V
GATE-EMITTER VOLTAGE, V_{GE}			± 20		V
COLLECTOR CURRENT, RMS Continuous, I_C			20		A
Pulsed, I_{CM}			35		A
POWER DISSIPATION @ $T_C = 25^\circ\text{C}$, P_T	100	100	75	75	W
Derate above $T_C = 25^\circ\text{C}$	0.8	0.8	0.6	0.6	W/ $^\circ\text{C}$
OPERATING AND STORAGE TEMPERATURE, T_j , T_{stg}			-55 to +150		$^\circ\text{C}$

Harris Semiconductor IGBT product is covered by one or more of the following U.S. patents:

4,364,073	4,417,385	4,430,792	4,443,931	4,466,176	4,532,534	4,567,641
4,587,713	4,618,872	4,620,211	4,631,564	4,639,754	4,639,762	4,641,162
4,644,637	4,682,195	4,684,413	4,717,679	4,794,432	4,801,986	4,803,533
4,809,045	4,810,665					

IGTH/IGTM/IGTP20N40 IGTH/IGTM/IGTP20N50
IGTH/IGTM/IGTP20N40A IGTH/IGTM/IGTP20N50A

ELECTRICAL CHARACTERISTICS, At Case Temperature ($T_c = 25^\circ\text{C}$) unless otherwise specified

CHARACTERISTICS	SYMBOL	TEST CONDITIONS	LIMITS				UNITS
			RCH20N40	RCH20N40A	RCH20N50	RCH20N50A	
			RCM20N40	RCM20N40A	RCM20N50	RCM20N50A	
			RCP20N40	RCP20N40A	RCP20N50	RCP20N50A	
			Min.	Max.	Min.	Max.	
Collector-Emitter Breakdown Voltage	BV_{CES}	$I_C = 1\text{ mA}$ $V_{GE} = 0$	400	—	500	—	V
Gate Threshold Voltage	$V_{GE(th)}$	$V_{GE} = V_{CE}$ $I_C = 1\text{ mA}$	2	4.5	2	4.5	V
Zero-Gate Voltage Collector Current	I_{CES}	$V_{CE} = 400\text{ V}$	—	250	—	—	μA
		$V_{CE} = 500\text{ V}$	—	—	—	250	
		$T_C = 125^\circ\text{C}$	—	—	—	—	
		$V_{CE} = 400\text{ V}$ $V_{CE} = 500\text{ V}$	—	1000	—	—	
			—	—	—	1000	
Gate-Emitter Leakage Current	I_{GES}	$V_{GE} = \pm 20\text{ V}$ $V_{CE} = 0$	—	100	—	100	nA
Reverse Collector-Emitter Leakage Current	I_{CE}	$R_{GE} = 0\ \Omega$ $V_{EC} = 5\text{ V}$	—	-5	—	-5	mA
Collector-Emitter On Voltage	$V_{CE(on)}$	$I_C = 20\text{ A}$ $V_{GE} = 10\text{ V}$	—	2.5	—	2.5	V
		$I_C = 35\text{ A}$ $V_{GE} = 20\text{ V}$	—	3.2	—	3.2	
Gate-Emitter Plateau Voltage	V_{GEP}	$I_C = 10\text{ A}$ $V_{CE} = 10\text{ V}$	—	6 (typ.)	—	6 (typ.)	V
On-State Gate Charge	$Q_g(on)$	$I_C = 10\text{ A}$ $V_{CE} = 10\text{ V}$	—	33 (typ.)	—	33 (typ.)	nC
Turn-On Delay Time	$t_d(on)$	$I_C = 20\text{ A}$	—	50	—	50	ns
Rise Time	t_r	$V_{CE(CL)} = 300\text{ V}$	—	50	—	50	
Turn-Off Delay Time	$t_d(off)$	$L = 25\ \mu\text{H}$	—	400	—	400	
Fall Time	t_f	$T_J = 100^\circ\text{C}$	Typ.	—	Typ.	—	
	20N40 20N50	$V_{GE} = 10\text{ V}$ $R_g = 25\ \Omega$	680	1000	680	1000	
	20N40A 20N50A		400	500	400	500	
Turn-Off Energy Loss per Cycle (off switching dissipation = E_{off} x frequency)	E_{off}	$I_C = 10\text{ A}$	1810 (typ.)				μJ
	20N40 20N50	$V_{CE(CL)} = 300\text{ V}$ $L = 25\ \mu\text{H}$ $T_J = 100^\circ\text{C}$					
	20N40A 20N50A	$V_{GE} = 10\text{ V}$ $R_g = 25\ \Omega$	1070 (typ.)				
Thermal Resistance Junction-to-Case	$R_{\theta JC}$	IGTH/IGTM	—	1.25	—	1.25	$^\circ\text{C/W}$
		IGTP	—	1.67	—	1.67	

IGTH/IGTM/IGTP20N40
IGTH/IGTM/IGTP20N40A

IGTH/IGTM/IGTP20N50
IGTH/IGTM/IGTP20N50A

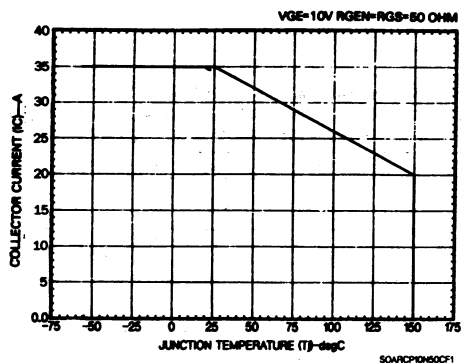


Fig. 1 - Maximum switching current level for all types. $R_0 = 25 \Omega$, $V_{GE} = 0 \text{ V}$ are the minimum allowable values.

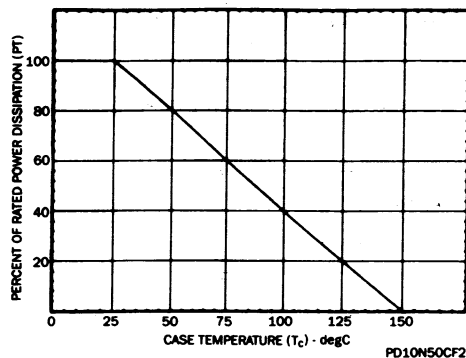


Fig. 2 - Power dissipation vs. temperature derating curve for all types.

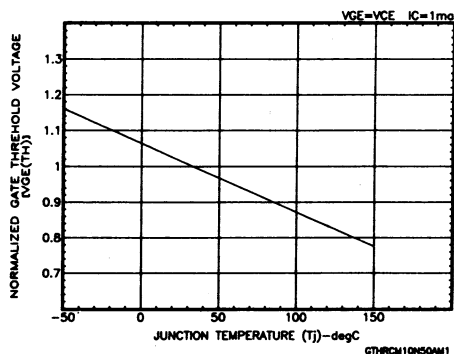


Fig. 3 - Typical normalized gate threshold voltage as a function of junction temperature for all types.

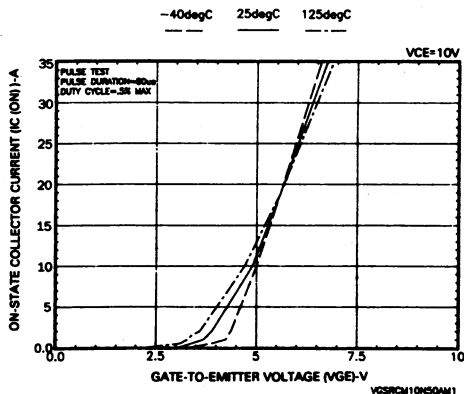


Fig. 4 - Typical transfer characteristics for all types.

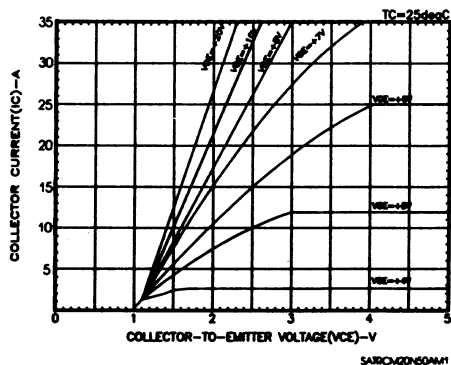


Fig. 5 - Typical saturation characteristics for all types.

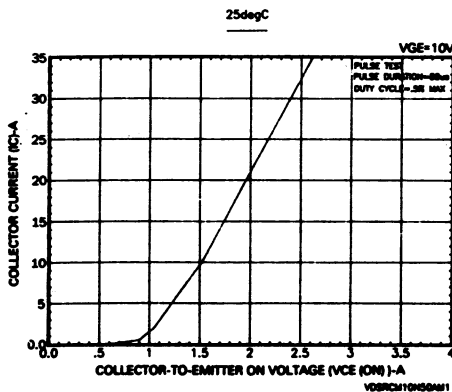


Fig. 6 - Typical collector-to-emitter on-voltage as a function of collector current for all types.

IGTH/IGTM/IGTP20N40
 IGTH/IGTM/IGTP20N40A

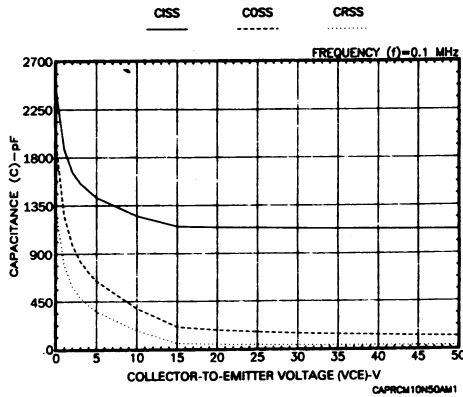
 IGTH/IGTM/IGTP20N50
 IGTH/IGTM/IGTP20N50A


Fig. 7 - Capacitance as a function of collector-to-emitter voltage for all types.

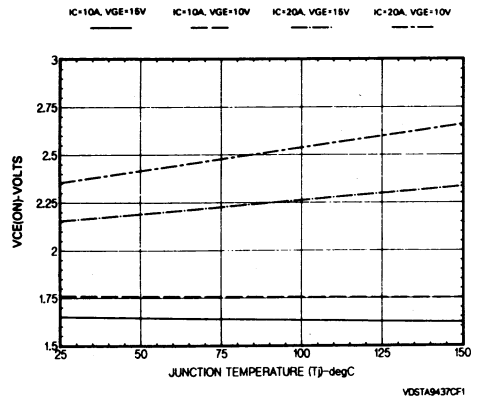


Fig. 8 - Typical VCE (on) vs. temperature for all types.

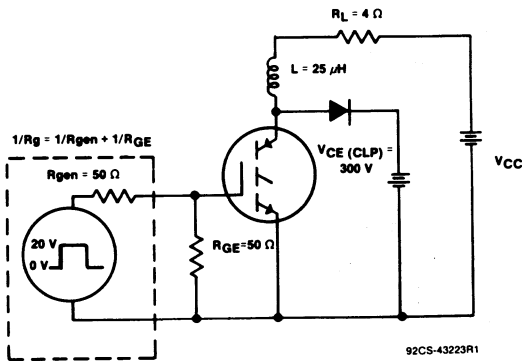


Fig. 9 - Inductive switching test circuit.

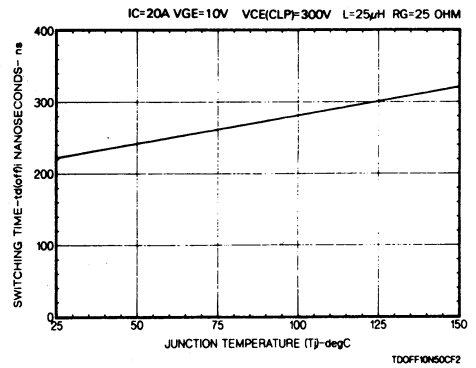


Fig. 10 - Typical turn-off delay time for all types.

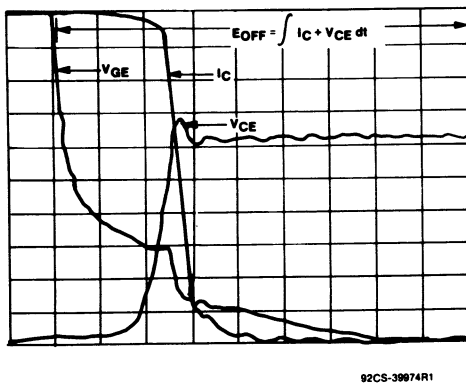


Fig. 11 - Typical inductive switching waveforms.

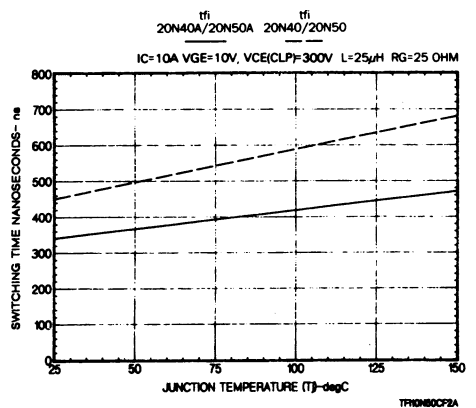


Fig. 12 - Typical fall time for all types.

IGTH/IGTM/IGTP20N40 IGTH/IGTM/IGTP20N50
IGTH/IGTM/IGTP20N40A IGTH/IGTM/IGTP20N50A

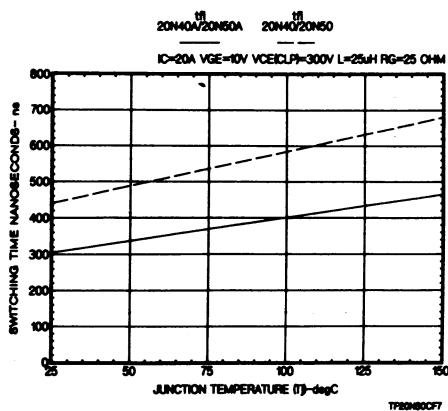


Fig. 13 - Typical fall time for all types ($I_C = 20 A$).

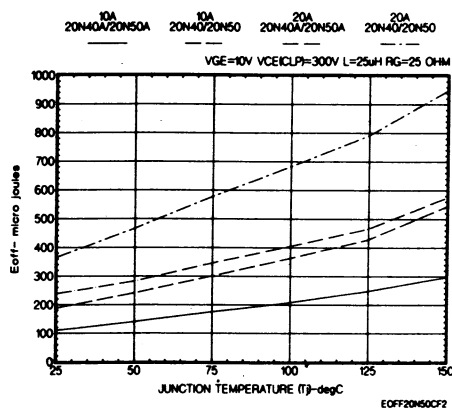
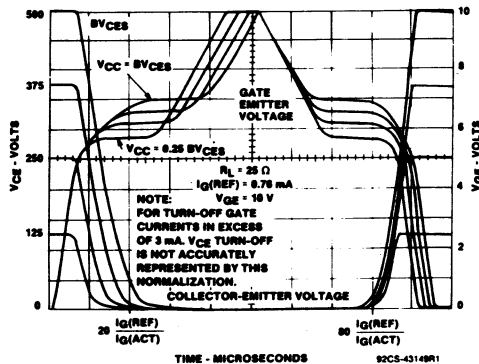


Fig. 14 - Typical clamped inductive turn-off switching loss/cycle.



Refer to RCA application notes AN-7254 and AN-7260 on the use of normalized switching waveforms.

Fig. 15 - Normalized switching waveforms at constant gate current.

N-Channel Enhancement-Mode Insulated Gate Bipolar Transistors (IGBTs) With Anti-Parallel Ultra-Fast Diode

20 A, 400 V and 500 V

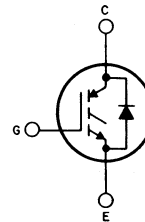
 $V_{CE(on)}$: 2.5 V Maximum T_{fall} : 1 μ s, 0.5 μ s**Features:**

- Low on-state voltage
- Fast switching speeds
- High input impedance
- Anti-parallel diode

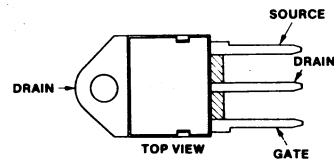
Applications:

- Power supplies
- Motor drives
- Protective circuits

The IGTH20N40D, IGTH20N40AD, IGTH20N50D, and IGTH20N50AD are n-channel enhancement-mode conductivity modulated field-effect transistors (IGBTs) designed for high voltage, low on-dissipation applications such as switching regulators and motor drivers. They feature a discrete anti-parallel diode that shunts current around the IGBT in the reverse direction without introducing carriers into the depletion region. These types can be operated directly from low power integrated circuits. They are supplied in the JEDEC TO-218AC plastic package and are fabricated using the TA9573 and TA9616 dies.

N-CHANNEL ENHANCEMENT MODE

92CS-43516

TERMINAL DIAGRAM**TERMINAL DESIGNATION****JEDEC TO-218AC****MAXIMUM RATINGS, Absolute-Maximum Values ($T_C = 25^\circ\text{C}$):**

	IGTH20N40D IGTH20N40AD	IGTH20N50D IGTH20N50AD	
COLLECTOR-EMITTER VOLTAGE	400	500	V
COLLECTOR-GATE VOLTAGE ($R_{ge} = 1\text{ M}\Omega$)	400	500	V
GATE-EMITTER VOLTAGE			V
COLLECTOR CURRENT, RMS Continuous			A
Pulsed	± 20		A
POWER DISSIPATION at $T_C = 25^\circ\text{C}$	20		W
Derate above $T_C = 25^\circ\text{C}$	35		W
OPERATING AND STORAGE TEMPERATURE	100		$^\circ\text{C}$
	0.8		
	-55 to +150		

Harris Semiconductor IGBT product is covered by one or more of the following U.S. patents:

4,364,073	4,417,385	4,430,792	4,443,931	4,466,176	4,532,534	4,567,641
4,587,713	4,618,872	4,620,211	4,631,564	4,639,754	4,639,762	4,641,162
4,644,637	4,682,195	4,684,413	4,717,679	4,794,432	4,801,986	4,803,533
4,809,045	4,810,665					

IGTH20N40D, IGTH20N40AD, IGTH20N50D, IGTH20N50AD

ELECTRICAL CHARACTERISTICS, At Case Temperature ($T_C = 25^\circ\text{C}$) unless otherwise specified

CHARACTERISTIC		TEST CONDITIONS	LIMITS				UNITS
			IGTH20N40D IGTH20N40AD		IGTH20N50D IGTH20N50AD		
			MIN.	MAX.	MIN.	MAX.	
Collector-Emitter Breakdown Voltage	BV_{CES}	$I_C = 1\text{ mA}$ $V_{GE} = 0$	400	—	500	—	V
Gate Threshold Voltage	$V_{GE(th)}$	$V_{GE} = V_{CE}$ $I_C = 1\text{ mA}$	2	4.5	2	4.5	
Zero-Gate Voltage Collector Current	I_{CES}	$V_{CE} = 400\text{ V}$	—	250	—	—	μA
		$V_{CE} = 500\text{ V}$	—	—	—	250	
		$T_C = 125^\circ\text{C}$	—	—	—	—	
		$V_{CE} = 400\text{ V}$ $V_{CE} = 500\text{ V}$	—	1000	—	1000	
Gate-Emitter Leakage Current	I_{GES}	$V_{GE} = \pm 20\text{ V}$ $V_{CE} = 0$	—	100	—	100	nA
Collector-Emitter On-Voltage	$V_{CE(on)}$	$I_C = 20\text{ A}$ $V_{GE} = 10\text{ V}$	—	2.5	—	2.5	V
		$I_C = 35\text{ A}$ $V_{GE} = 20\text{ V}$	—	3.2	—	3.2	
Gate-Emitter Plateau Voltage	V_{GEP}	$I_C = 10\text{ A}$ $V_{CE} = 10\text{ V}$	—	6 (typ)	—	6 (typ)	
On-State Gate Charge	$Q_G(on)$	$I_C = 10\text{ A}$ $V_{CE} = 10\text{ V}$	—	33(typ)	—	33(typ)	nC
Turn-On Delay Time	$t_d(on)$	$I_C = 20\text{ A}$ $V_{CE(clp)} = 300\text{ V}$ $L = 25\text{ }\mu\text{H}$ $T_J = 100^\circ\text{C}$ $V_{GE} = 10\text{ V}$ $R_\theta = 25\text{ }\Omega$	—	50	—	50	ns
Rise Time	t_r		—	50	—	50	
Turn-Off Delay Time	$t_d(off)$		—	400	—	400	
Fall Time	t_{fi}		TYP		TYP		
	20N40D 20N50D 20N40AD 20N50AD		680 1000 TYP 400	1000 680 TYP 500	1000 680 TYP 400	1000 1000 500	
Turn-Off Energy Loss per Cycle (off switching dissipation = E_{off} x frequency)	E_{off}	$I_C = 20\text{ A}$ $V_{CE(clp)} = 300\text{ V}$ $L = 25\text{ }\mu\text{H}$ $T_J = 100^\circ\text{C}$ $V_{GE} = 10\text{ V}$ $R_\theta = 25\text{ }\Omega$	1810 (typ)				μJ
	20N40D 20N50D 20N40AD 20N50AD		1070 (typ)				
Thermal Resistance Junction-to-Case	$R\theta_{JC}$		—	1.25	—	1.25	$^\circ\text{C/W}$
Diode Forward Voltage	V_{EC}	$I_{EC} = 20\text{ A}$	—	2	—	2	V
Diode Reverse Recovery Time	T_{rr}	$I_{EC} = 20\text{ A}$ $di/dt = 100\text{ A}/\mu\text{s}$	—	100	—	100	ns

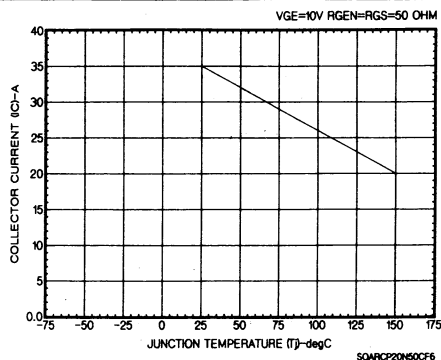


Fig. 1 - Maximum switching current level for all types.
Minimum allowable values are $R_\theta = 50\text{ }\Omega$, $V_{GE} = 0\text{ V}$.

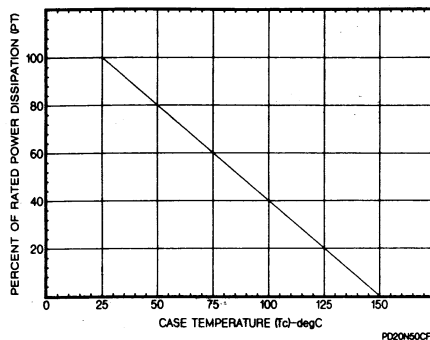


Fig. 2 - Power dissipation vs. temperature derating curve for all types.

IGTH20N40D, IGTH20N40AD, IGTH20N50D, IGTH20N50AD

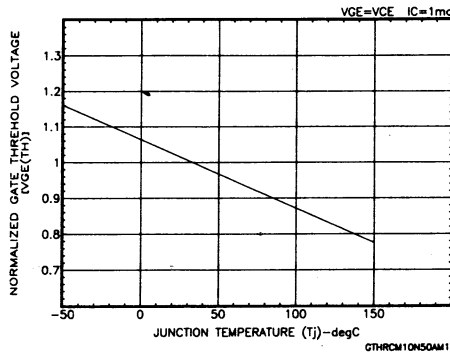


Fig. 3 - Typical normalized gate-threshold voltage as a function of junction temperature for all types.

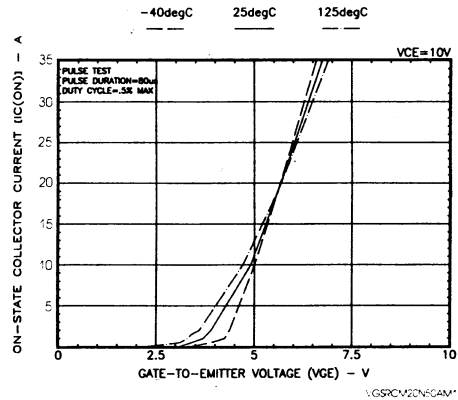


Fig. 4 - Typical transfer characteristics for all types.

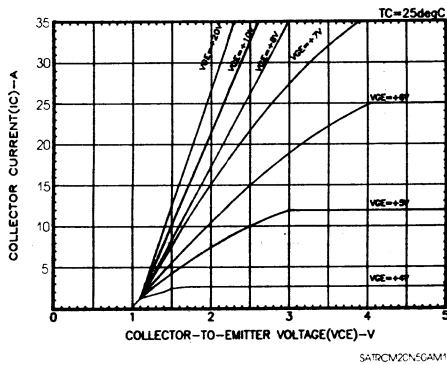


Fig. 5 - Typical saturation characteristics for all types.

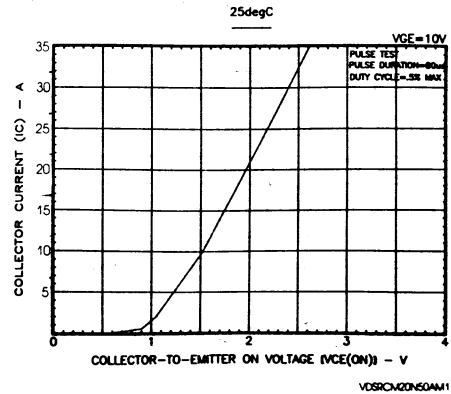


Fig. 6 - Typical collector-to-emitter on-voltage as a function of collector current for all types.

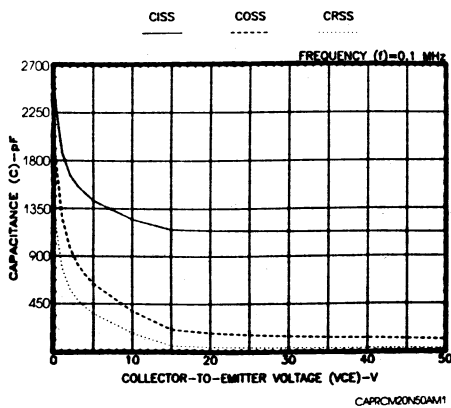


Fig. 7 - Capacitance as a function of collector-to-emitter voltage for all types.

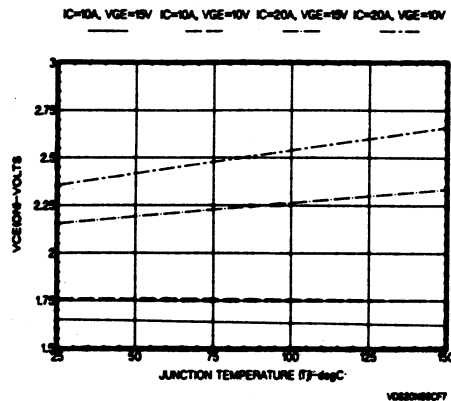


Fig. 8 - Typical $V_{CE(ON)}$ vs. temperature for all types.

IGTH20N40D, IGTH20N40AD, IGTH20N50D, IGTH20N50AD

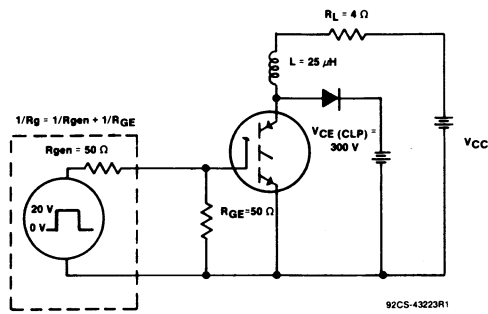


Fig. 9 - Inductive switching test circuit.

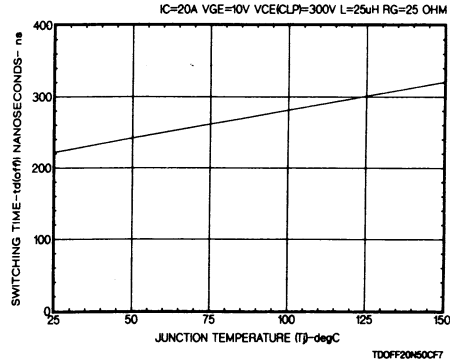


Fig. 10 - Typical turn-off delay time for all types.

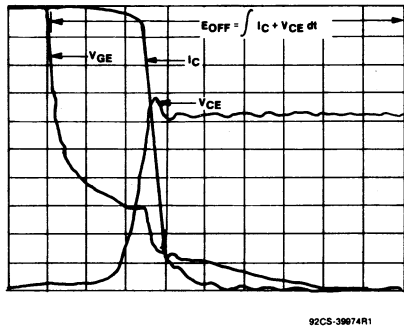


Fig. 11 - Typical inductive switching waveforms.

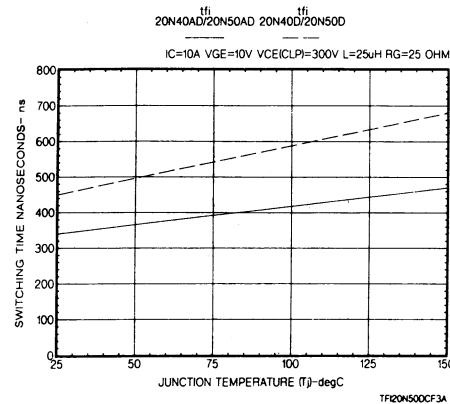


Fig. 12 - Typical fall time for all types ($I_C = 10\ A$).

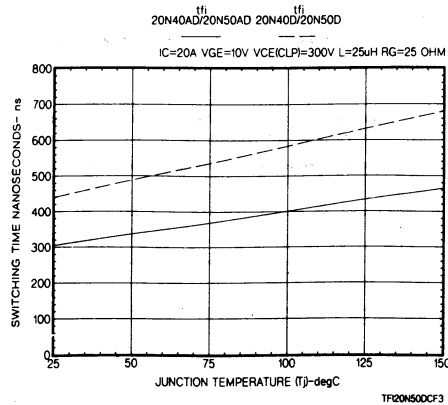


Fig. 13 - Typical fall time for all types ($I_C = 20\ A$).

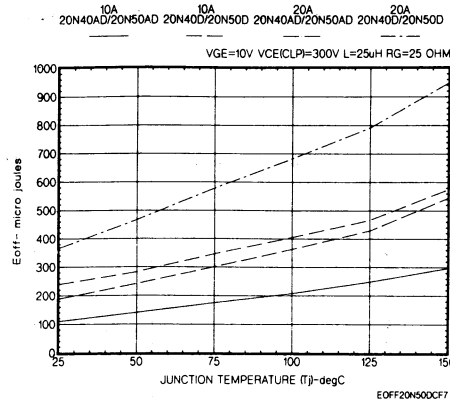


Fig. 14 - Typical clamped inductive turn-off switching loss/cycle.